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Business Model; 5.4 The Fabless ASIC Model: How It Works; 5.5 The Services and Capabilities of a Fabless ASIC Supplier; 5.6 Conclusion; Chapter 6: Electronic Design Automation; 6.1 Fabless EDA Overview; 6.2 Fabless EDA Selection Process; 6.3 Physical Design EDA; Chapter 7: Intellectual Property; 7.1 SIP Industry Overview; 7.2 SIP Business Environment; 7.3 Sourcing SIP Products; 7.4 Baseline Terminology; 7.5 Finding SIP and Related Products; 7.6 Evaluating SIP Business Models; 7.7 SIP Product Enablers
7.8 Examples by SIP Product Type7.9 Licensing SIP Products; 7.10 Provider and Buyer Perspectives; 7.11 The Evolution of the IP Industry; 7.12 Intellectual Property Considerations; 7.13 IP Outsourcing; 7.14 Making IP Work in the Fabless Semiconductor Community; 7.15 IP Acquisition Considerations for Fabless IC Companies; Chapter 8: e-Commerce; 8.1 The Virtual Fab Challenge; 8.2 Semiconductor & Fabless Manufacturing: What is Different?; 8.3 ""Build to Forecast"" for Outsourced Manufacturing; 8.4 ERP System Solutions; 8.5 The Information Ecosystem: Where Communication is Key
Chapter 9: Quality and Reliability9.1 General; 9.2 Front-End; 9.3 Back-End; 9.4 Environment, Health and Safety; Chapter 10: Test Development; 10.1 Simplifying Outsourced Test Development; 10.2 Preparation; 10.3 Evaluation; 10.4 Conclusion; PART 3 - Becoming a Best-in-Class Fabless Company; Chapter 11: Best Practices for Fabless Companies; 11.1 Achieving Best-in-Class Operations Practices; 11.2 A Foundry Manager's Role in a Fabless Company; 11.3 Closing the Loop: Understanding the Manufacturing Flow; 11.4 Managing a Virtual Manufacturing Chain; Chapter 12: Building the Right Partnerships
12.1 Suppliers are (Almost) Just as Important as Customers

Sommario/riassunto

Fabless (no fabrication) IC (integrated circuit) techniques are growing rapidly and promise to become the standard method of IC manufacturing in the near future, this book will provide readers with what will soon be required knowledge of the subject. Other books on IC fabrication deal with the strictly physical process aspects of the topic and assume all factors in IC fabrication are under the control of the IC designing company. By contrast, this title recognizing that fabless IC design is often as much about managing business relationships as it is about physical processes. "Fabless? ICs are